



6-layer PCB stackup



Parameters

material type:	Standard FR4 TG130
base materials thickness (after lamination):	0.960 mm
final PCB thickness:	1.13 mm ± 0.11 mm
Cu thickness:	
outer layers (base thickness, without plating):	18 μm
inner layers (final thickness):	35 μm / 35 μm / 35 μm / 35 μm